

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (previously presented) A template formed from a layered structure comprising:

a substrate;

a single-phase polymer layer positioned on the substrate; and

a semiconductor or metal layer positioned on the polymer layer;

wherein the polymer layer comprises a textured surface, the texturing being caused by induction of stress in the polymer layer with the semiconductor or metal layer present, after baking of the polymer layer at a temperature below the glass transition temperature of the polymer.

2. (canceled)

3. (previously presented) A template according to claim 1, wherein the single-phase polymer is selected from polymethylglutarimide (PMGI), polymethylmethacrylate (PMMA) and photoresist AZ5214E.

4. (currently amended) A template according to claim [[2]] 1, wherein the semiconductor or metal layer is a semiconductor and the semiconductor is germanium.

5. (previously presented) A template according to claim 1, wherein the substrate comprises silicon.

6. (previously presented) A template according to claim 1, wherein the textured surface comprises parallel grooves.

7. (previously presented) A template according to claim 1, wherein the thickness of the single-phase polymer layer is 50-300 nm.

8. (currently amended) A template according to claim [[2]] 1, wherein the thickness of the semiconductor or metal layer is approximately 10 nm.

Claims 9-26: Canceled

27. (previously presented) A template according to claim 1, wherein the textured surface has been stabilized by annealing after the induction of stress.